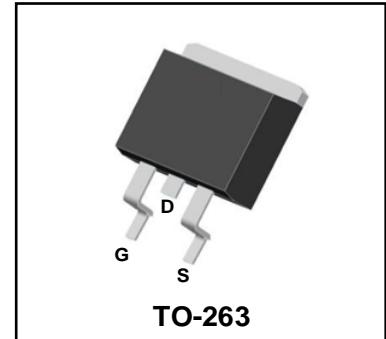
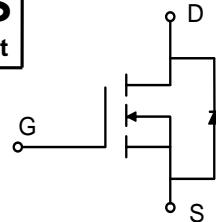


**80V N-Channel Enhancement Mode Power MOSFET****Description**

WMM90N08TS uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

**Features**

- $V_{DS} = 80V$ ,  $I_D = 90A$
- $R_{DS(on)} < 8.5m\Omega$  @  $V_{GS} = 10V$
- Green Device Available
- 100% EAS Guaranteed
- Optimized for High Speed Smooth Switching

**Applications**

- Synchronous Rectification
- DC/DC Converter
- Motor Control

**Absolute Maximum Ratings ( $T_c = 25^\circ C$ , unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	80	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current $T_c=25^\circ C$	$I_D$	90	A
$T_c=100^\circ C$		57	
Pulsed Drain Current <sup>4</sup>	$I_{DM}$	360	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	217.8	mJ
Total Power Dissipation	$P_D$	135.9	W
Operating Junction and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to 150	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	40	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	0.92	$^\circ C/W$

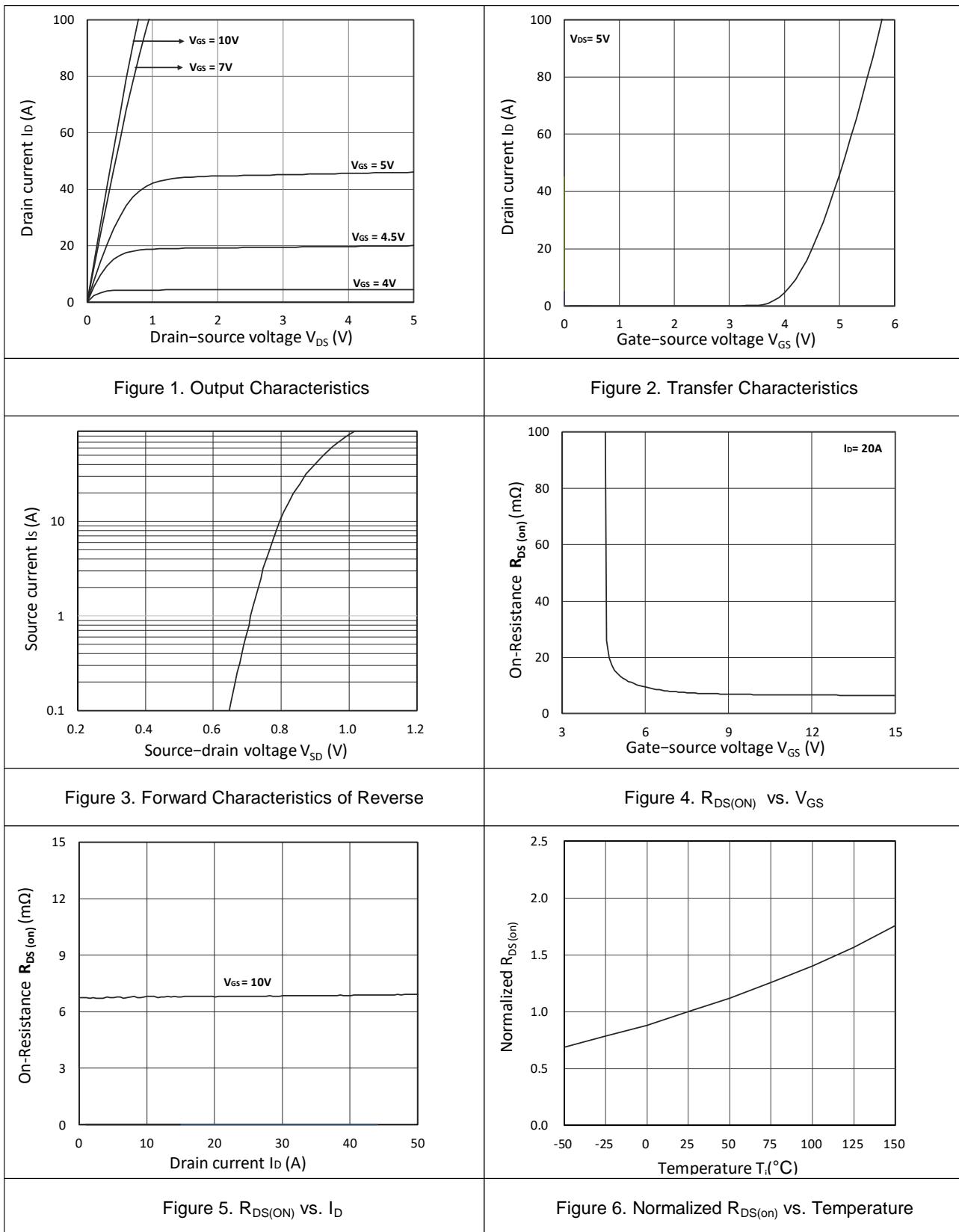
**Electrical Characteristics (T<sub>c</sub> = 25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	80	-	-	V
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current T <sub>J</sub> =25°C T <sub>J</sub> =100°C	I <sub>DSS</sub>	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V	-	-	1	μA
			-	-	100	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2	3	4	V
Drain-Source on-Resistance <sup>2</sup>	R <sub>D(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	6.7	8.5	mΩ
Forward Transconductance <sup>2</sup>	g <sub>f</sub> s	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A	-	43	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V, f = 1MHz	-	6495	-	pF
Output Capacitance	C <sub>oss</sub>		-	270	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	220	-	
<b>Switching Characteristics</b>						
Gate Resistance	R <sub>G</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz	-	0.7	-	Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 40V, I <sub>D</sub> = 20A	-	111	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	28.8	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	30	-	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 40V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = 20A	-	42	-	ns
Rise Time	t <sub>r</sub>		-	55	-	
Turn-off Delay Time	t <sub>d(off)</sub>		-	66	-	
Fall Time	t <sub>f</sub>		-	37	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	I <sub>S</sub> = 20A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>	I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	90	A

Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=30V, V<sub>GS</sub>=10V, L=0.4mH, I<sub>AS</sub>=33A
4. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.
5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

## Typical Characteristics



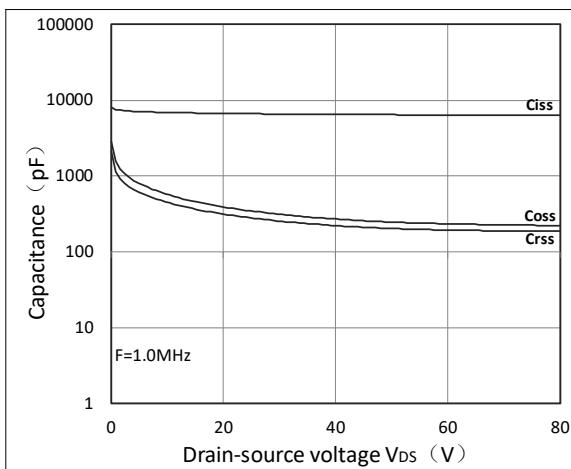


Figure 7. Capacitance Characteristics

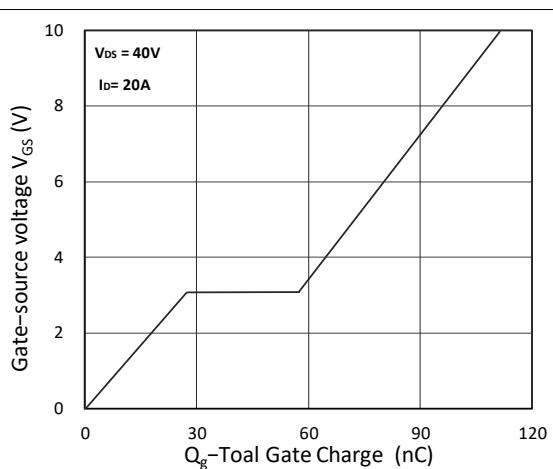


Figure 8. Gate Charge Characteristics

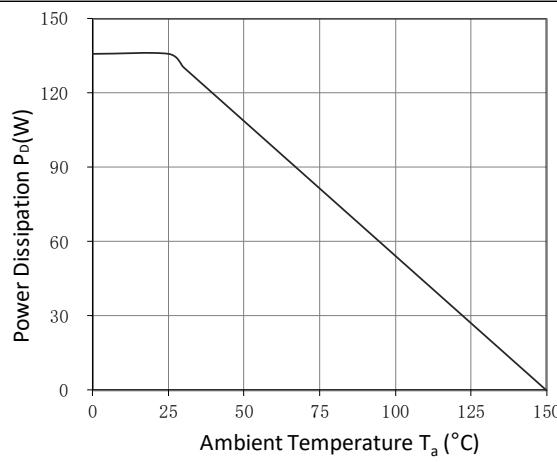


Figure 9. Power Dissipation

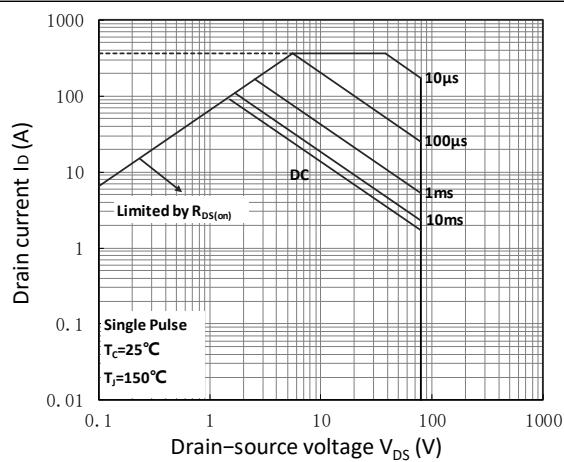


Figure 10. Safe Operating Area

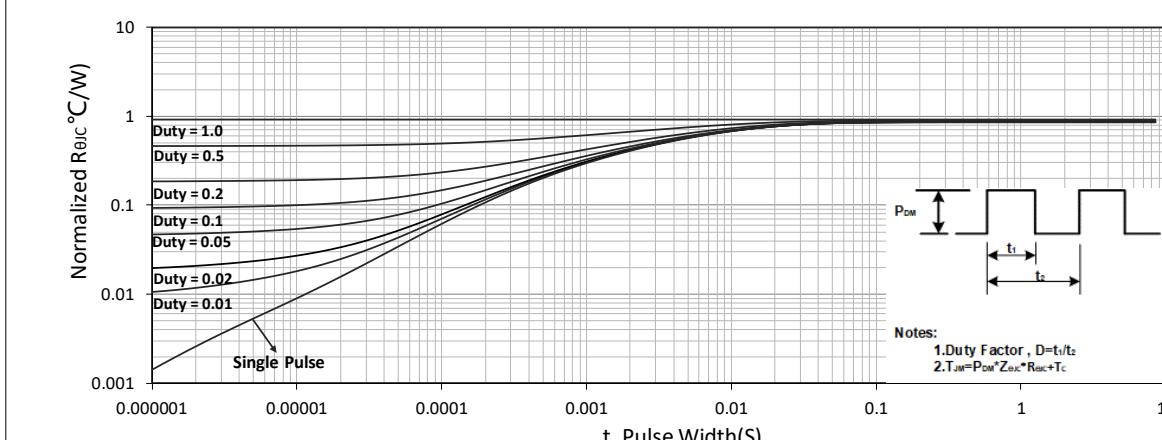
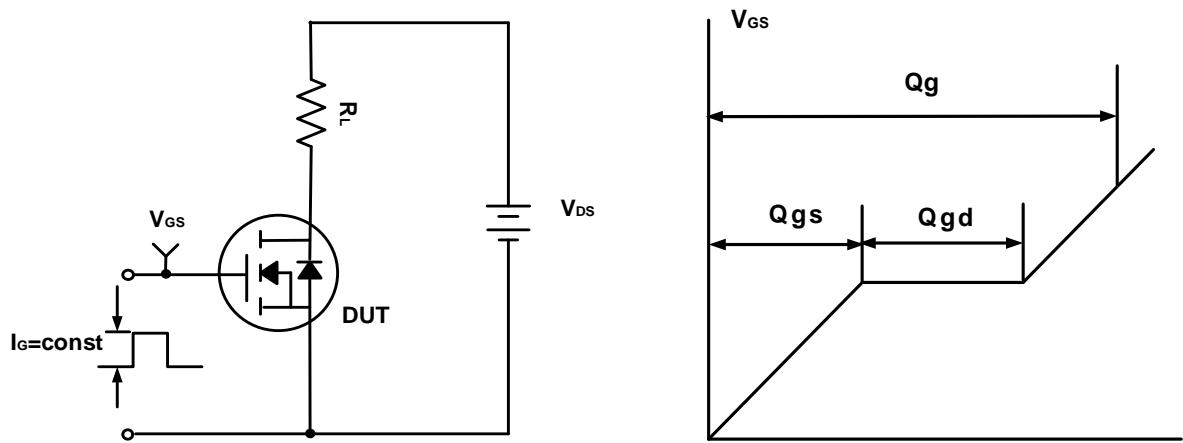
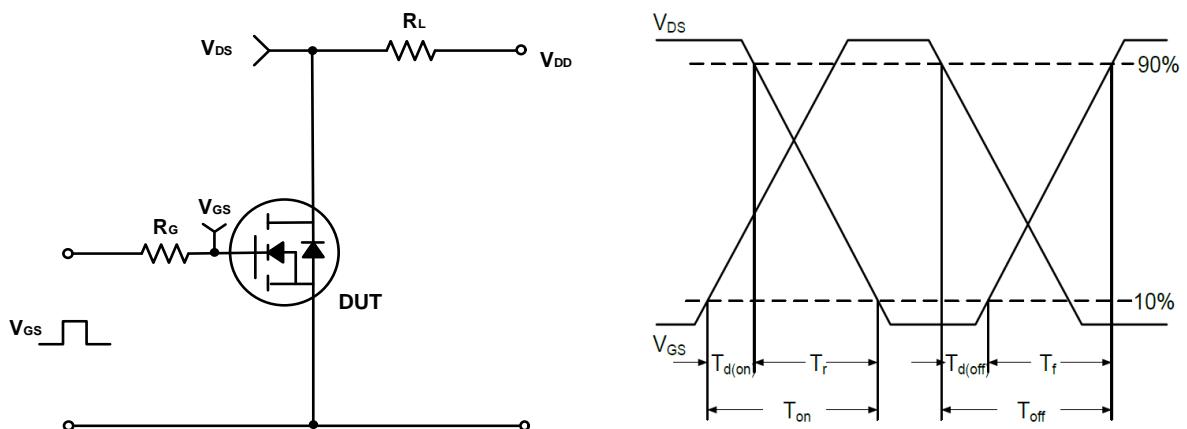
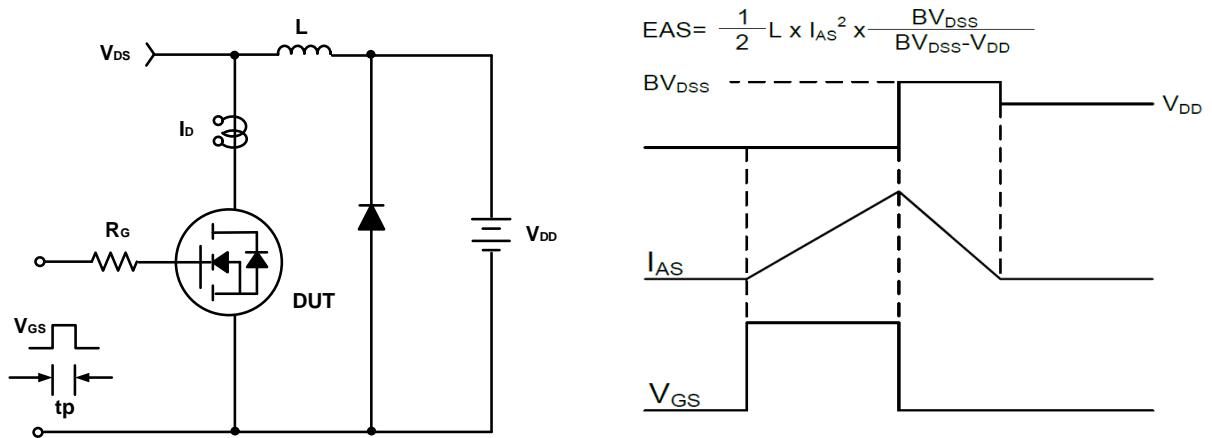
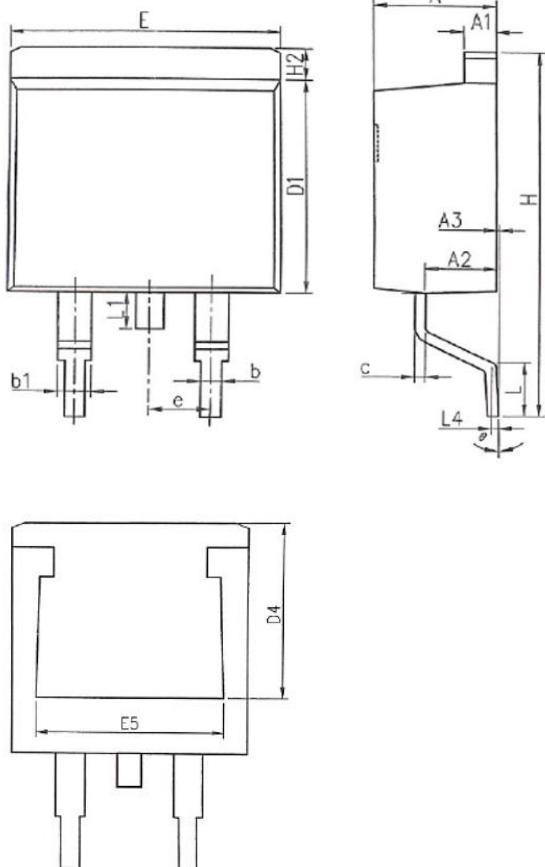


Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for TO-263

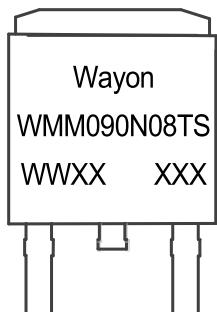
## COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	4.37	4.89
A1	1.17	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.28	0.60
D1	8.45	9.30
D4	6.60	-
E	9.80	10.40
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.80
L1	-	1.75
L4	0.254BSC	
θ	0°	9°

**Ordering Information**

Part	Package	Marking	Packing method
WMM90N08TS	TO-263	WMM90N08TS	Tape and Reel

**Marking Information**

WMM90N08TS = Device code

WWXX XXX= Date code

**Contact Information**

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WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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